

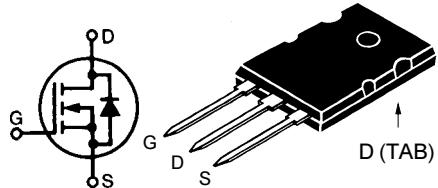
HiPerFET™ Power MOSFET

**IXFN170N10
IXFK170N10**

Single MOSFET Die

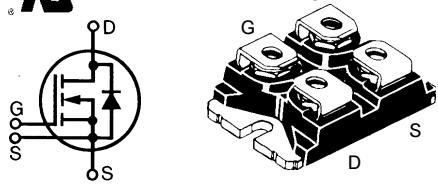
V_{DSS}	I_{D25}	$R_{DS(on)}$	t_{rr}
100V	170A	10mΩ	200ns
100V	170A	10mΩ	200ns

TO-264 AA (IXFK)



miniBLOC, SOT-227 B (IXFN)

E153432

G = Gate
S = SourceD = Drain
TAB = Drain

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

Features

- International standard packages
- Encapsulating epoxy meets UL 94 V-0, flammability classification
- miniBLOC with Aluminium nitride isolation
- Low $R_{DS(on)}$ HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- Fast intrinsic Rectifier

Applications

- DC-DC converters
- Synchronous rectification
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- Temperature and lighting controls
- Low voltage relays

Advantages

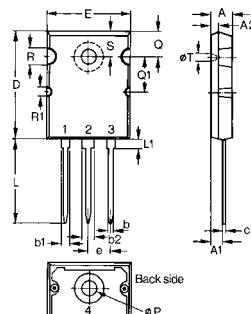
- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Maximum Ratings		
		IXFK 170N10	IXFN 170N10	
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	100	100	V
V_{DGR} ①	$T_J = 25^\circ\text{C}$ to 150°C	100	100	V
V_{GS}	Continuous	± 20	± 20	V
V_{GSM}	Transient	± 30	± 30	V
I_{D25}	$T_c = 25^\circ\text{C}$	170③	170	A
I_{D125} ④	$T_c = 125^\circ\text{C}$	76	NA	
I_{DM} ②	$T_c = 25^\circ\text{C}$, $T_c = 25^\circ\text{C}$	680	680	A
I_{AR}		170	170	A
E_{AR}	$T_c = 25^\circ\text{C}$	60	60	mJ
dv/dt	$I_s \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$ $T_J \leq 150^\circ\text{C}$, $R_G = 2 \Omega$	5	5	V/ns
P_D	$T_c = 25^\circ\text{C}$	560	600	W
T_J		-55 ... +150		°C
T_{JM}		150		°C
T_{stg}		-55 ... +150		°C
T_L	1.6 mm (0.063 in) from case for 10 s	300	N/A	°C
V_{ISOL}	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	t = 1 min t = 1 s	N/A N/A	2500 3000 V~ V~
M_d	Mounting torque Terminal connection torque	0.9/6 N/A	1.5/13 Nm/lb.in. 1.5/13 Nm/lb.in.	
Weight		10	30	g

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
V_{DSS}	$V_{GS} = 0 \text{ V}$, $I_D = 3 \text{ mA}$ V_{DSS} temperature coefficient	100	0.077	V %/K
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 8 \text{ mA}$ $V_{GS(th)}$ temperature coefficient	2	-0.183	4 V %/K
I_{GSS}	$V_{GS} = \pm 20 \text{ V}$, $V_{GS} = 0 \text{ V}$			± 200 nA
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS} \text{ V}$ $V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	400 2	μA mA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$, $I_D = 0.5 \cdot I_{D25}$ Pulse test, $t \leq 300 \text{ ms}$, duty cycle $d \leq 2 \%$			10 mΩ

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$, pulse test	65		S
C_{iss}		10,300		pF
C_{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	2,200		pF
C_{rss}		1,200		pF
$t_{d(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1 \Omega$ (External),	40	ns	
t_r		90	ns	
$t_{d(off)}$		158	ns	
t_f		79	ns	
$Q_{g(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$	515	nC	
Q_{gs}		62	nC	
Q_{gd}		276	nC	
R_{thJC}	TO-264 AA		0.22	K/W
R_{thCK}	TO-264 AA		0.15	K/W
R_{thJC}	miniBLOC, SOT-227 B		0.21	K/W
R_{thCK}	miniBLOC, SOT-227 B		0.05	K/W

TO-264 AA Outline



Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.82	5.13	.190	.202
A1	2.54	2.89	.100	.114
A2	2.00	2.10	.079	.083
b	1.12	1.42	.044	.056
b1	2.39	2.69	.094	.106
b2	2.90	3.09	.114	.122
c	0.53	0.83	.021	.033
D	25.91	26.16	1.020	1.030
E	19.81	19.96	.780	.786
e	5.46	BSC	.215	BSC
J	0.00	0.25	.000	.010
K	0.00	0.25	.000	.010
L	20.32	20.83	.800	.820
L1	2.29	2.59	.090	.102
P	3.17	3.66	.125	.144
Q	6.07	6.27	.239	.247
Q1	8.38	8.69	.330	.342
R	3.81	4.32	.150	.170
R1	1.78	2.29	.070	.090
S	6.04	6.30	.238	.248
T	1.57	1.83	.062	.072

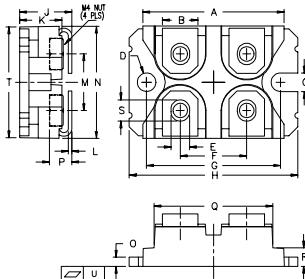
Source-Drain Diode

(T_J = 25°C, unless otherwise specified)

Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
I_s	$V_{GS} = 0$		170	A
I_{SM}	Repetitive; pulse width limited by T _{JM}		680	A
V_{SD}	$I_F = 100 \text{ A}, V_{GS} = 0 \text{ V},$ Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %		1.5	V
t_{rr}	$I_F = 50 \text{ A}, -di/dt = 100 \text{ A}/\mu\text{s}, V_R = 100 \text{ V}$	175	ns	
Q_{RM}		1.1	μC	
I_{RM}		12.6	A	

- Notes:
1. $R_{GS} = 1 \text{ M}\Omega$
 2. Pulse width limited by T_{JM}.
 3. Chip capability
 4. Current limited by external leads

miniBLOC, SOT-227 B



M4 screws (4x) supplied

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	38.00	38.23	1.496	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.76	0.84	0.030	0.033
M	12.60	12.85	0.496	0.506
N	25.15	25.42	0.990	1.001
O	1.98	2.13	0.078	0.084
P	4.95	5.97	0.195	0.235
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.174
S	4.72	4.85	0.186	0.191
T	24.59	25.07	0.968	0.987
U	-0.05	0.1	-0.002	0.004

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715 4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025

Figure 1. Output Characteristics at 25°C

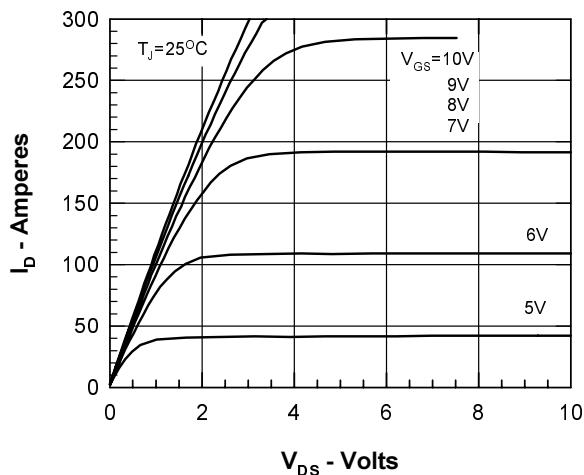


Figure 3. $R_{DS(on)}$ normalized to 0.5 I_{D25} value vs. I_D

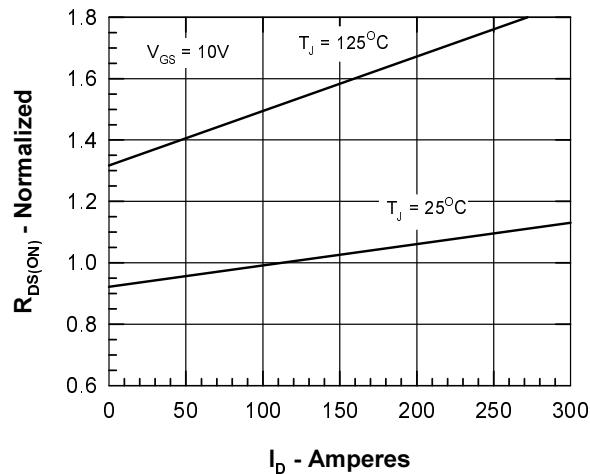


Figure 5. Drain Current vs. Case Temperature

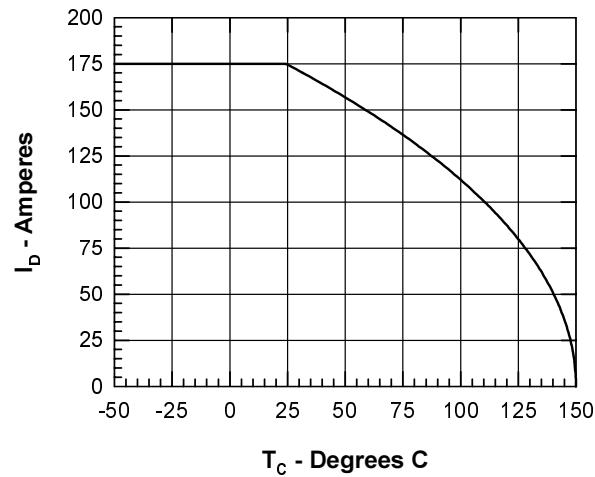


Figure 2. Output Characteristics at 125°C

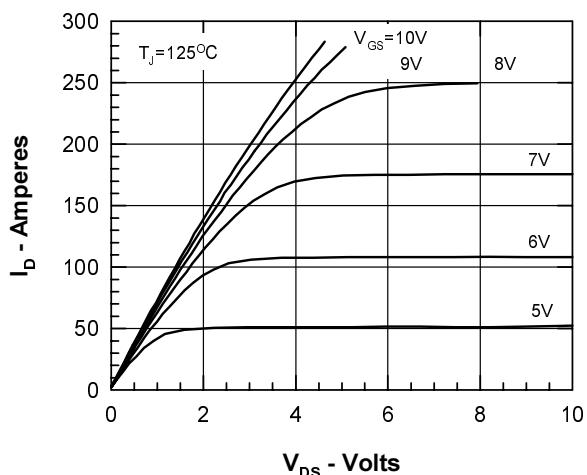


Figure 4. $R_{DS(on)}$ normalized to 0.5 I_{D25} value vs. T_J

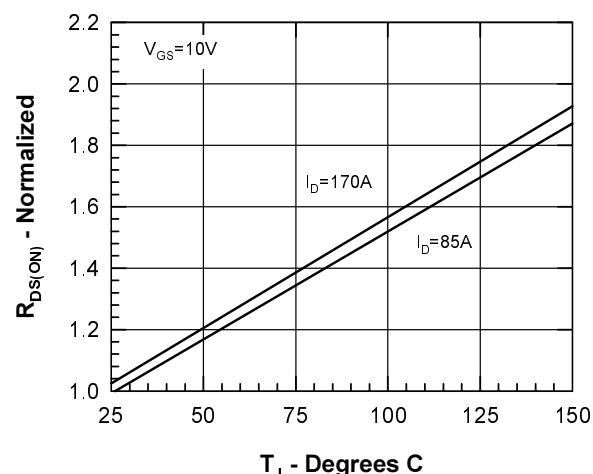


Figure 6. Admittance Curves

